

FEATURES

- | 2100W Peak Pulse Power per Line (tp=8/20μs)
- | Uni-directional configurations
- | Low clamping voltage
- | Low leakage current
- | Response Time is Typically < 1 ns
- | Solid-state silicon-avalanche technology

APPLICATIONS

- | Power supply protection
- | Handsets and Accessories
- | Personal Digital Assistants(PDA's)
- | Portable Instrumentation
- | Industrial equipment
- | Notebooks, Desktops, and Servers



DFN1610



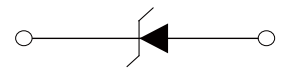
Marking

IEC COMPATIBILITY

- | IEC61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
- | IEC61000-4-4 (EFT) 40A (5/50ns)

APPROVALS

- | | |
|-------------|------------------------------------|
| RoHS | Compliance with 2011/65/EU |
| HF | Compliance with IEC61249-2-21:2003 |



Schematic Symbol

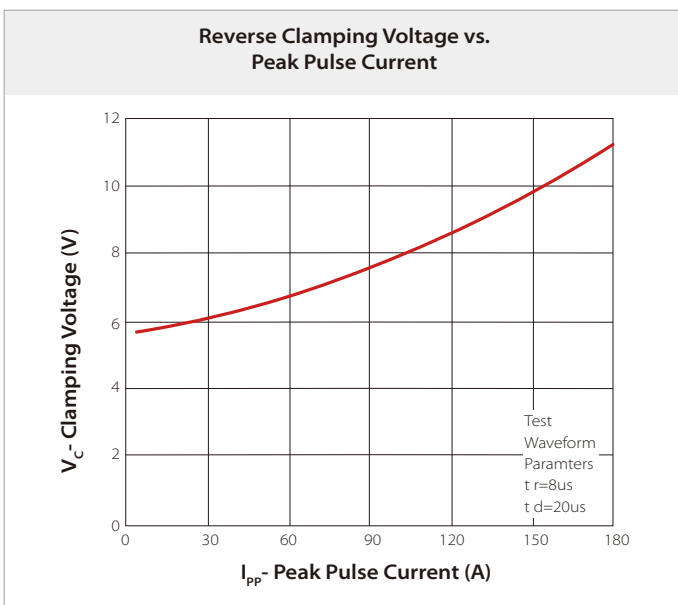
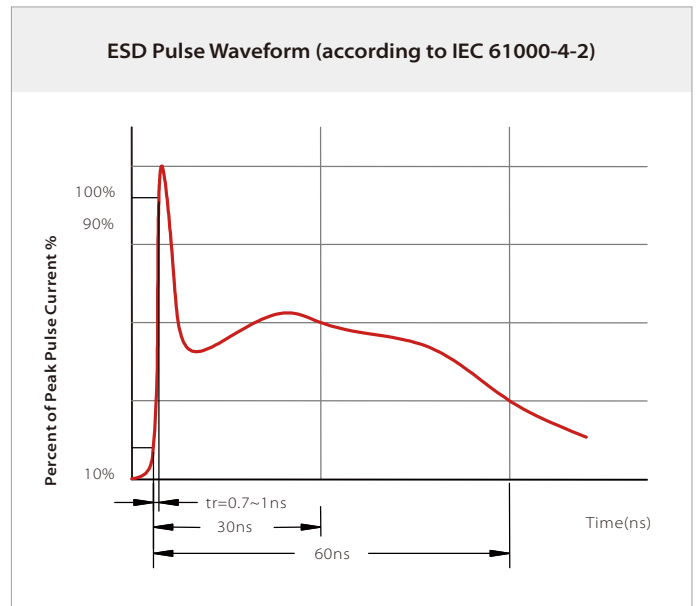
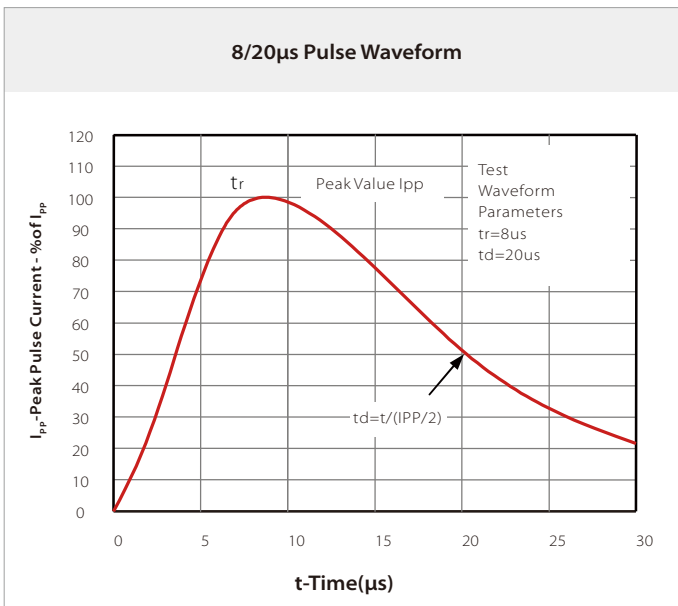
THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
P_{PP}	Peak Pulse Power (tp=8/20μs waveform)	2100	Watts
T_J	Operating Temperature Range	-55 to +125	°C
T_{STG}	Storage Temperature Range	-55 to +125	°C

ELECTRICAL CHARACTERISTICS

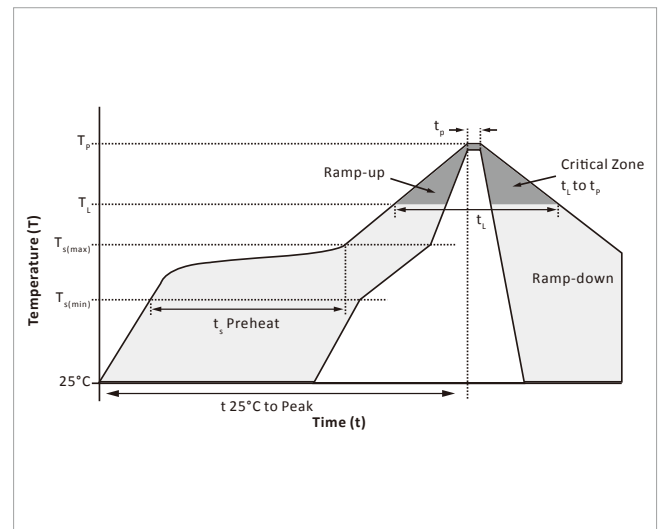
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{RWM}	Reverse Stand-off Voltage				4.5	V
V_{BR}	Reverse Breakdown Voltage	$I_T=1mA$	4.6			V
I_R	Reverse Leakage Current	$V_{RWM}=4.5V$			1	μA
V_F	Forward Voltage	$I_F=10mA$	0.6		1.2	V
V_C	Clamping Voltage (Tp=8/20us)	$I_{pp}=180A, tp=8/20us$			12	V
I_{pp}	Peak Pulse Current (Tp=8/20us)	tp=8/20us			180	A
C_J	Off State Junction Capacitance	$V_R=0V, f=1MHz$		380	450	pF

CHARACTERISTIC CURVES

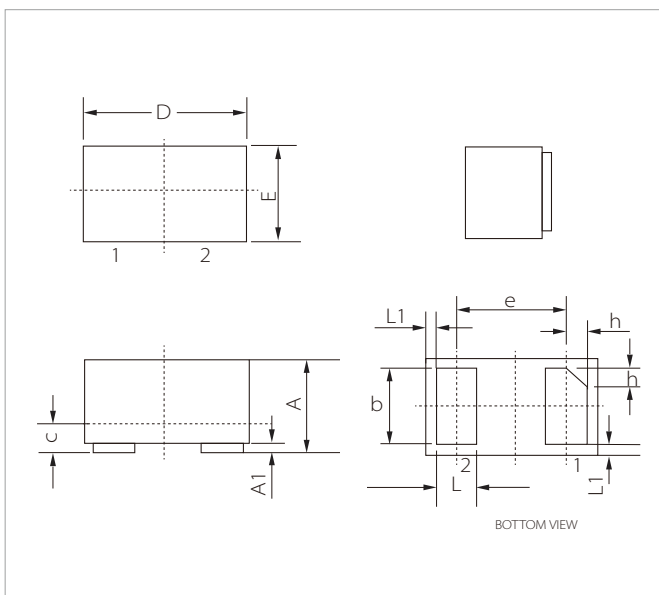


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_p)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

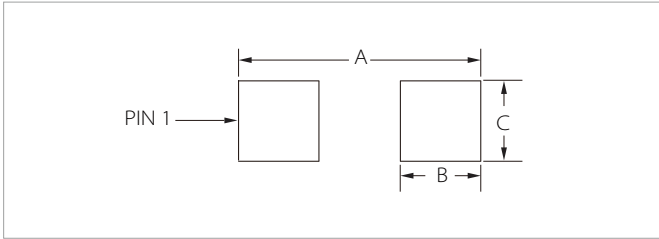


DFN1610 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.45	0.55	0.018	0.022
A1	0	0.05	0	0.002
b	0.75	0.85	0.030	0.033
c	0.10	0.20	0.004	0.008
D	1.55	1.65	0.061	0.065
e	1.10TYP		0.043TYP	
E	0.95	1.05	0.037	0.041
L	0.35	0.45	0.014	0.018
L1	0.05REF		0.002REF	
h	0.15	0.25	0.006	0.010

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
A	1.85	0.073
B	0.625	0.025
C	1.00	0.039

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE16F200U4.5A	DFN1610	10000PCS	7"

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